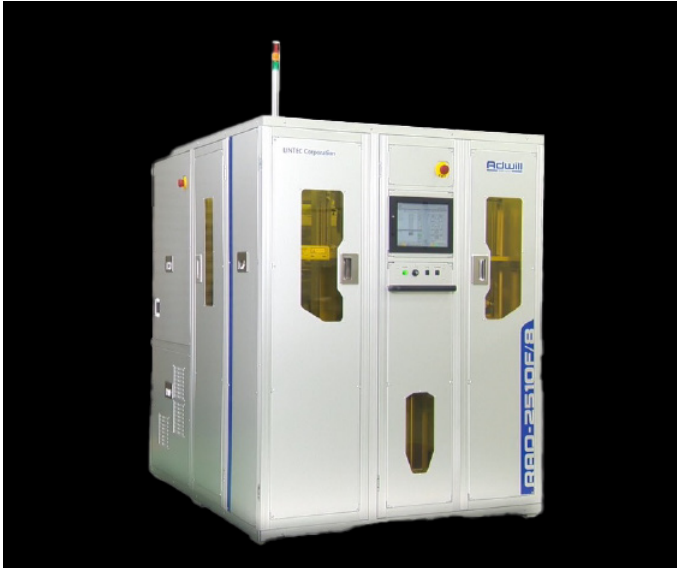


Wafer Mounter

RAD-2510F/8



Facility

Power Supply	Voltage	: AC200-230V±10% (AC190-253V)
	Frequency	: 50/60Hz
	Phase	: Single phase
Air Supply	Power consumption	: 1.5kW
	Air pressure	: 0.6-0.8MPa
	Air consumption	: <300L/min (ANR)
Vacuum Supply	Vacuum pressure	: <-80kPa

Applicable Wafer Size 100mm、125mm、150mm、200mm

Size
Width(W) : 1,360mm
Depth(D) : 1,830mm
Height(H) : 1,800mm
(excluding the signal tower and protruding parts)

Weight 1,500kg

UPH 120wafers/hour

The above processing capacity is based on following conditions:

Wafer : 200mm non-polished mirror wafer
Dicing tape : G-11D from LINTEC

Outline

- Fully-Automatic wafer mounter that is compatible with thin/warped wafers.
- Realization of high throughput by the optimization of transfer units.
- Reduction of tape consumption from the decrease in in-line pre-cutting tape pitch.

Options

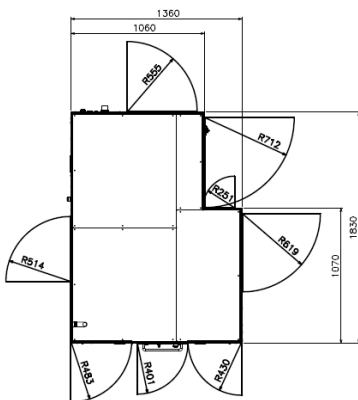
- Double Loader and Double Unloader Specification
- Dicing Tape In-Line Pre-Cutting
- Attachment Table Heater Specification
- Vision System (Wafer ID Reader & Barcode Attachment System)
- Host Communication Function (Communication Format: Conforms to SECS-I and HSMS/Software: Conforms to GEM)
- ESD Compatibility

Suitable Tape

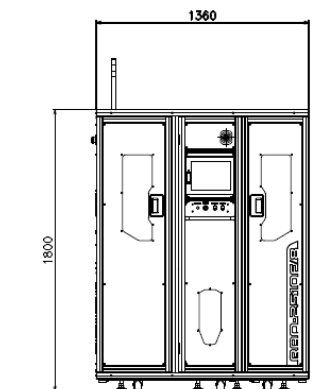
- Dicing Tape: Adwill D Series, G Series
- Dicing Die Bonding Tape: Adwill LE Tape
- Backside Coating tape: Adwill LC Tape

External View

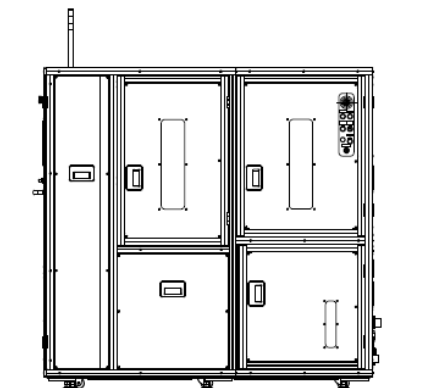
Unit:mm



Top View



Front View



Right Side View



LINTEC Corporation *Linking your dreams*

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<https://www.adwill-global.com/en>